

REV.	SPECIFICATION	ECN NO.	APPD.

4876-xxG00D1T

4876-xxG00D3T-x

Material:

Housing:LCP, UL94V-0.

Contacts: Phosphor Bronze, Gold Plated over Nickel 30 u" Min.

Solder Pad: Brass, 30 u" Min Nickel Plated.

Electrical Characteristics:

Voltage Rating: AC30V.

Current Rating: 0.5 AMP.

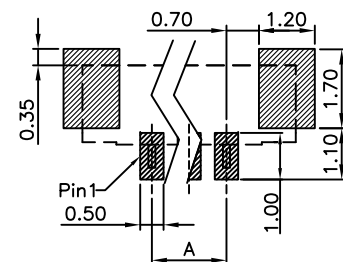
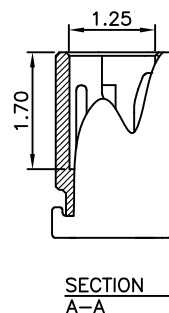
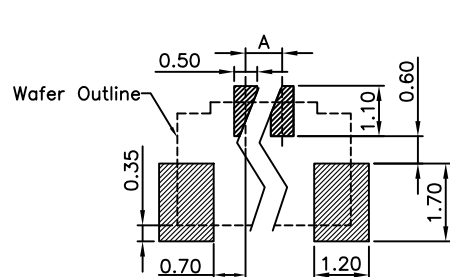
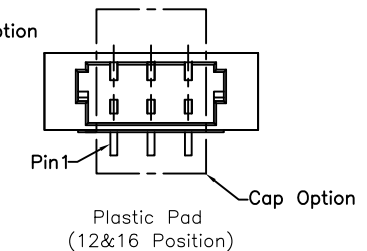
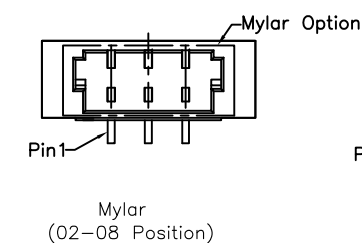
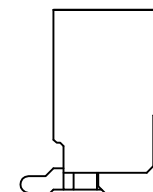
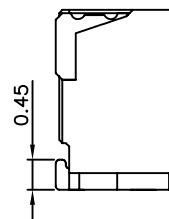
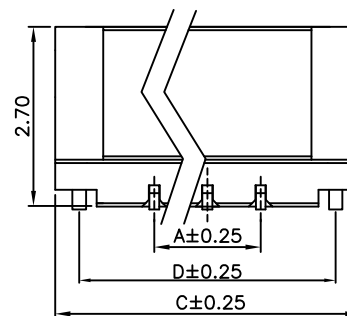
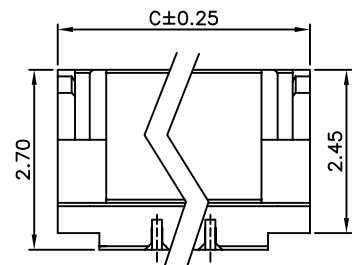
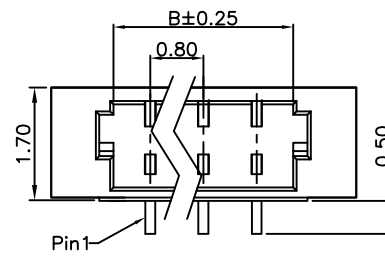
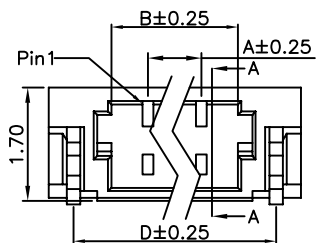
Dielectric Withstanding Voltage: AC 200V For 1 minute.

Insulation Resistance: 100MΩ min. at DC 200V.

Contact Resistance: 20mΩ max.

Operating Temperature: -25°C~+85°C.

***RoHS Compliant**



P.C.Board Layout

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4876-xxG00DxTx-x
Series: 4876-
No. of Pin: xx
G: Gold Plated
00: G/F
D: SMD Type
S: Mylar
P: Plastic Pad
T: Tape & Reel Package
1: Side Entry
3: Top Entry

Position	Dimension			
	A	B	C	D
2	0.80	1.90	3.78	3.04
3	1.60	2.70	4.58	3.84
4	2.40	3.50	5.38	4.64
5	3.20	4.30	6.18	5.44
6	4.00	5.10	6.98	6.24
7	4.80	5.90	7.78	7.04
8	5.60	6.70	8.58	7.84
10	7.20	8.30	10.18	9.44
12	8.80	9.90	11.78	11.04
14	10.40	11.50	13.38	12.64
16	12.00	13.10	14.98	14.24
20	15.20	16.30	19.18	17.44

Tolerances	Dwg No.	4876D02001		Title: 4876 Series 0.8mm Wafer S.M.D Type		 OUPIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 4876-xxG00DxTx-x				
x = ±0.50	Projection					SHEET 1/1 Ver.No. B2				
.x = ±0.25	Unit	mm	Scale							1:1
.xx = ±0.15	Drawn By	jia-chi 12/04'17								
				0704						